

SLPC2018

The Third Smart Laser Processing Conference 2018

April 24 (Tuesday) to April 26 (Thursday), 2018

Pacifico Yokohama, Yokohama, Japan

<http://www.jlps.gr.jp/slpc2018/>

Organized by Japan Laser Processing Society (JLPS)



Co-located with Optics & Photonics International Congress 2018 (OPIC2018)

Aim and Scope

Laser beam processing is played an important role in industrial fields of not only macro-products but also micro-products, and its technologies are essential to open the new strategies of smart manufacturing such as highly integrated, accurate, efficient processing with low energy consumption. SLPC2018 deals with science and technology of smart laser materials processing including micro and macro laser processing. SLPC2018 is planned as a three-day event with a plenary session, oral sessions and poster session. The aim of this conference is to provide a forum for discussion of fundamental aspects of laser-matter interaction, the state-of-the-art of smart laser processing, and topics for the next generation with fundamental scientists, end users and laser manufacturers. We expect that SLPC2018 would play an important role not only for understanding fundamental knowledge of laser processing but also forecasting future technologies and the future laser processing fields. During the conference, Optics and Photonics International Exhibition is held jointly at the conference site.

Topics and Fields

Cutting

Additive Manufacturing / Selective Laser Melting

Functional Surface Manufacturing

Laser Polishing / Cleaning

Micro Nano Processing

Advanced Lasers and Optical Technologies

Industrial Applications

Welding

Cladding / Laser Metal Deposition

Laser Peening and Related Phenomena

Short Wavelength Application

Ultrashort Pulsed Laser Processing

CFRP Processing

Others

Important Dates

Registration due date for Presenting Authors :

March 5, 2018, JST

Early-bird Registration ends:

April 5, 2018, JST

Invited Speakers

Plenary Speakers:

Prof. Dr. Andreas Ostendorf, Ruhr University Bochum, Germany
"Laser processing in flexible electronics"

Prof. Masahiro Tsukamoto, JWRI, Osaka University, Japan
Talk title: To be announced

Invited Speakers:

Mr. Bastian Becker, TRUMPF Corporation, Japan
"Latest trends of IoT and additive laser manufacturing"

Dr. Yohei Kobayashi, University of Tokyo, Japan
"Toward cool laser manufacturing"

Dr. Markus Kogel-Hollacher, Precitec GmbH & Co. KG, Germany
"Sensors in laser materials processing: Are they finally ready to take the lead?"

Dr. Jean-Michel Pelaprat, NUBURU, USA
"High power blue lasers development for copper material processing"

Mr. Markus Antonius Ruetering, Laserline GmbH, Germany
"Latest diode laser technology and its industrial applications"

Dr. Koji Tojo, Simadzu Corporation, Japan
"High brightness blue direct diode laser for advanced materials processing"

Registration (OPIC2018)

Website: <https://opicon.jp/registration>

	Type	On/Before April 5, 2018	After April 6
Member*	Conference (General)	JPY 55,000-	JPY 60,000-
	Student, Retiree	JPY 18,000-	JPY 21,000-
Non-member	Conference (General)	JPY 65,000-	JPY 70,000-
	Student, Retiree	JPY 21,000-	JPY 23,000-

*Member of specialized international conference organizations

Special Events

- SLPC 2018 Evening Reception: April 24
- OPIC 2018 Plenary session will be held in the morning of April 25
For further information, see: <https://opicon.jp/program/plenarysession>
- Joint sessions with SLPC 2018, LIC 18 (Laser Ignition Conference) and PLD 18 (Pacific-rim Laser Damage Conference) will be held in the afternoon of April 25
- OPIC 2018 Reception: April 25 (18:00-20:00)

Registered attendees for the SLPC 2018 are invited to attend all of the above events for free.

Co-operating Societies and Media Partners

Laser Institute of America (LIA)



Association of Industrial Laser Users (AILU)



Verein Schweizer Laser und Photonik Netz
(Swissphotonics)



Wissenschaftliche Gesellschaft Lasertechnik e.V.
(WLT)



Sponsors

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Committee Members

Conference Chairs:

Masahiro Tsukamoto, JWRI, Osaka University, Japan

Reinhart Poprawe, Fraunhofer Institute for Laser Technology, Germany

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Andreas Ostendorf, Ruhr-University Bochum, Germany

Koji Sugioka, RIKEN, Japan

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Togo Shinonaga, Okayama University, Japan

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